



CIRCUIT  
PROTECTION  
SOLUTIONS



Littelfuse Technologies: Power Thyristors • Protection Arrays • Fuses • PTCs • Varistors • TVS Diodes • GDTs • ESD Suppressors • SIDACTor Devices

# Introduction to Silicon Protection Arrays



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Updated 09/21/2010

# Outline

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- **ESD Protection**
  - Test Pulse Waveforms
  - Compare w/ Lightning
- **Key Parameters**
  - $V_{RWM}$
  - $V_{BR}$  or  $V_R$
  - $V_C$
  - Capacitance
  - $V_{ESD}$
  - $I_P$  or  $I_{PP}$
- **Configurations**
  - Grounded TVS Diode Arrays (SP03)
  - TVS Rail Clamp Diode Arrays (SP30xx, SP40xx)
  - TVS Arrays (SP10xx, SP050x)
  - SCR Array Rail Clamps (SP72x)
  - EMI Filter Arrays (SP60xx)
- **PC Board Layout Issues**
  - Close to the input
  - Avoiding stub traces
  - Paralleling channels
- **Package Options**
  - Micro Packages
  - MSOP Packages
  - Power Packages



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# ElectroStatic Discharge Protection

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Lightning



AC Power  
Contact



Sustained  
Overload

ESD is one of four major threats to electronic equipment.  
Protecting equipment against ESD is a \$500M market



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# ESD is FAST!!

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- AC Power Contact tests are measured in milliseconds
  - 1000 milliseconds = 1 second
- Lightning pulses are measured in microseconds
  - 1000 microseconds = 1 millisecond
- ESD pulses are measured in nanoseconds
  - 1000 nanoseconds = 1 microsecond

An object traveling at the speed of light can go:

- Around Earth more than 7 times in one second
- 186 miles or 300 km in one millisecond
- 1000 feet or 300 m in one microsecond
- 1 foot or 30 cm in one nanosecond



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# ESD Test Waveforms

## IEC 61000-4-2

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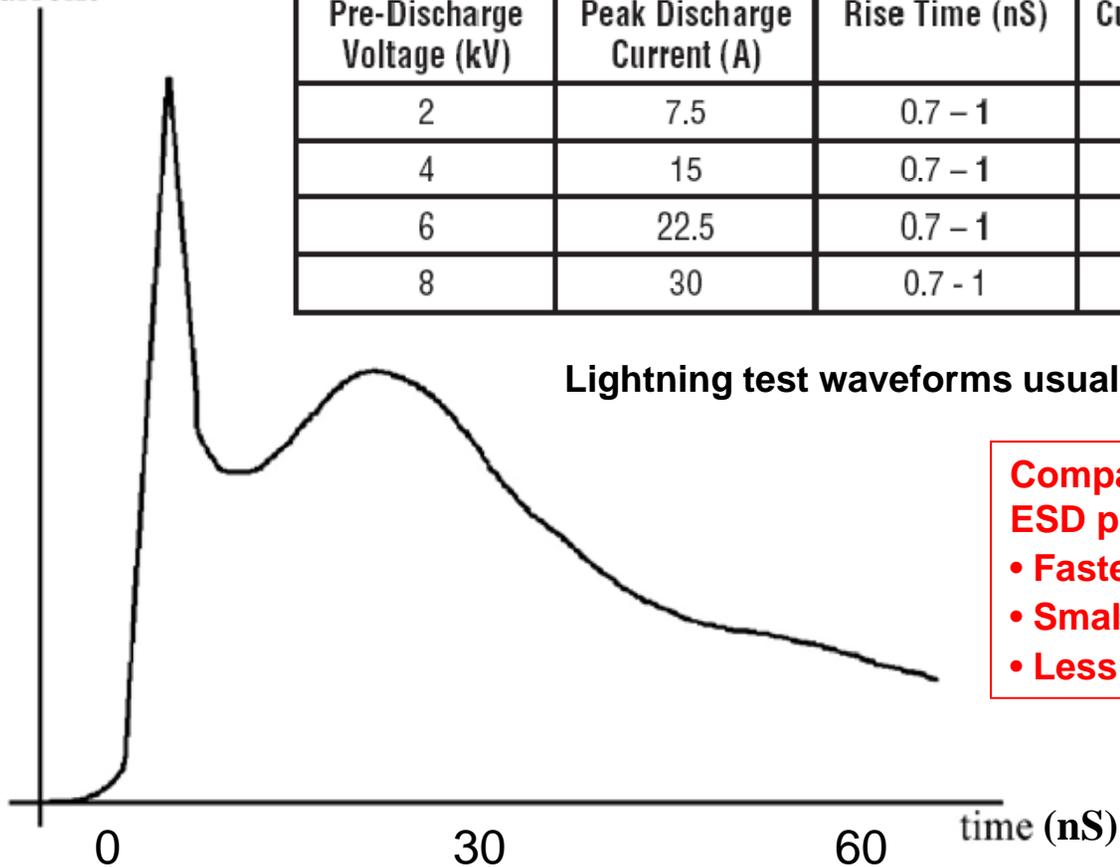
current

Pre-Discharge Voltage (kV)	Peak Discharge Current (A)	Rise Time (nS)	Current at 30 nS	Current at 60 nS
2	7.5	0.7 - 1	4	2
4	15	0.7 - 1	8	4
6	22.5	0.7 - 1	12	6
8	30	0.7 - 1	16	8

Lightning test waveforms usually peak at 100A – 500A.

Compared to lightning protectors, ESD protectors are:

- Faster
- Smaller
- Less robust



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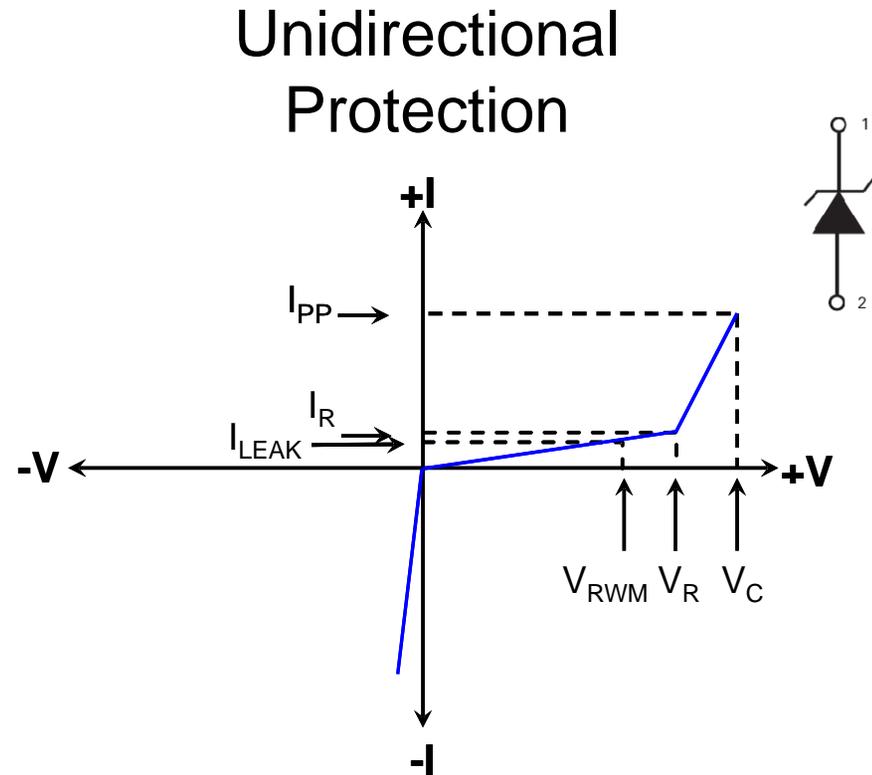
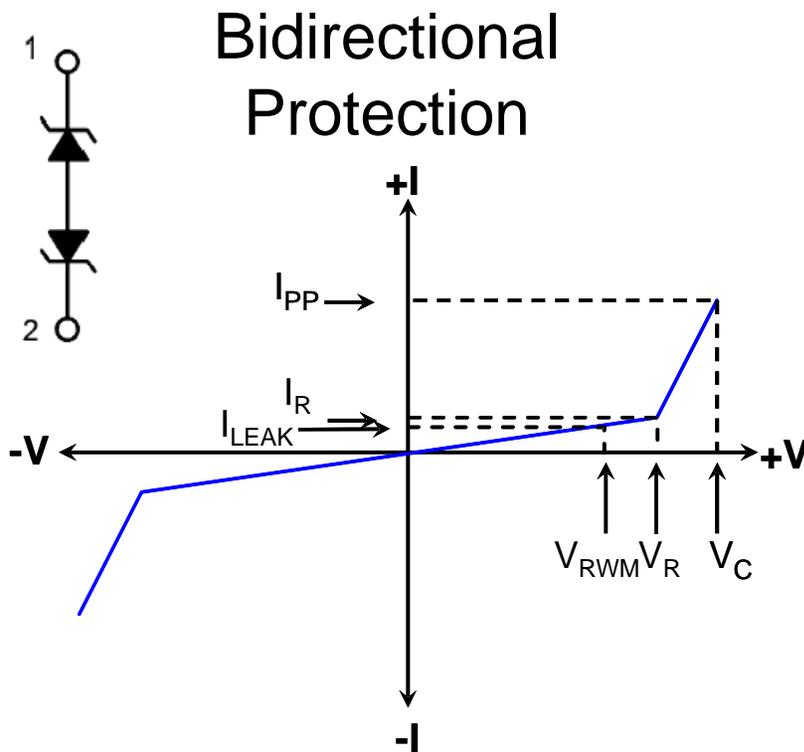


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# Bidirectional vs. Unidirectional

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Voltage – Current (V-I) Curve

- Voltage is displayed left to right
- Current is displayed up and down



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# Key Parameters: $V_{RWM}$

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- The Reverse Standoff Voltage or  $V_{RWM}$  is the maximum voltage that can be applied to the ESD protector without activating the device.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Forward Voltage Drop	$V_F$	$I_F=10mA$	0.7	0.9	1.2	V
Reverse Voltage Drop	$V_R$	$I_R=1mA$	7.0	7.8	8.5	V
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$			5.5	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=5V$			0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_r=8/20\mu s, Fwd$		8.0	11.0	V
		$I_{PP}=2A, t_p=8/20\mu s, \Gamma w d$		9.7	13.0	V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.7		$\Omega$
ESD Withstand Voltage <sup>1,2</sup>	$V_{ESD}$	IEC61000-4-2 (Contact)	$\pm 15$			kV
		IEC61000-4-2 (Air)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V		12		pF
		Reverse Bias=2.5V		8		pF
		Reverse Bias=5V		7		pF



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## Key Parameters: $V_R$

- The Reverse Voltage Drop or  $V_R$  is the voltage at which the device will begin to break down and begin to protect.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Forward Voltage Drop	$V_F$	$I_F=10\text{mA}$	0.7	0.9	1.2	V
Reverse Voltage Drop	$V_R$	$I_R=1\text{mA}$	7.0	7.9	8.5	V
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu\text{A}$			5.5	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=5\text{V}$			0.5	$\mu\text{A}$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1\text{A}, t_r=8/20\mu\text{s}, \text{Fwd}$		8.0	11.0	V
		$I_{PP}=2\text{A}, t_p=3/20\mu\text{s}, \text{Fwd}$		9.7	13.0	V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.7		$\Omega$
ESD Withstand Voltage <sup>1,2</sup>	$V_{ESD}$	IEC61000-4-2 (Contact)	$\pm 15$			kV
		IEC61000-4-2 (Air)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V		12		pF
		Reverse Bias=2.5V		8		pF
		Reverse Bias=5V		7		pF



# Key Parameters: $V_C$



- The Clamp Voltage or  $V_C$  is the maximum voltage that will appear across the device during the specified surge event.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Forward Voltage Drop	$V_F$	$I_F=10mA$	0.7	0.9	1.2	V
Reverse Voltage Drop	$V_R$	$I_R=1mA$	7.0	7.8	8.5	V
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$			5.5	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=5V$			0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_r=8/20\mu s, Fwd$		8.0	11.0	V
		$I_{PP}=2A, t_p=3/20\mu s, \Gamma w d$		9.7	13.0	V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.7		$\Omega$
ESD Withstand Voltage <sup>1,2</sup>	$V_{ESD}$	IEC61000-4-2 (Contact)	$\pm 15$			kV
		IEC61000-4-2 (Air)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V		12		pF
		Reverse Bias=2.5V		8		pF
		Reverse Bias=5V		7		pF



# Key Parameters: Capacitance



Electrical Characteristics (T <sub>OP</sub> =25°C)						
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Reverse Standoff Voltage	V <sub>RWM</sub>	I <sub>R</sub> ≤ 1μA			6.0	V
Reverse Leakage Current	I <sub>LEAK</sub>	V <sub>R</sub> =5V, Any I/O to GND		0.1	0.5	μA
Clamp Voltage <sup>1</sup>	V <sub>C</sub>	I <sub>PP</sub> =1A, t <sub>p</sub> =8/20μs, Fwd		10.8		V
		I <sub>PP</sub> =2A, t <sub>p</sub> =8/20μs, Fwd		12.3		V
Dynamic Resistance	R <sub>DYN</sub>	(V <sub>C2</sub> - V <sub>C1</sub> ) / (I <sub>PP2</sub> - I <sub>PP1</sub> )		1.5		Ω
ESD Withstand Voltage <sup>1</sup>	V <sub>ESD</sub>	IEC61000-4-2 (Contact)	±8			kV
		IEC61000-4-2 (Air)	±15			kV
Diode Capacitance <sup>1</sup>	C <sub>I/O-GND</sub>	Reverse Bias=0V		0.45		pF

- Capacitance adversely affects high data rate signals. Lower capacitance s always better.
- Capacitance may be specified at various bias voltages or between various pins.



# Key Parameters: $V_{ESD}$

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Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Forward Voltage Drop	$V_F$	$I_F=10mA$	0.7	0.9	1.2	V
Reverse Voltage Drop	$V_R$	$I_R=1mA$	7.0	7.8	8.5	V
Reverse Standoff Voltage	$V_{RWM}$	$I_R \leq 1\mu A$			5.5	V
Reverse Leakage Current	$I_{LEAK}$	$V_R=5V$			0.5	$\mu A$
Clamp Voltage <sup>1</sup>	$V_C$	$I_{PP}=1A, t_p=8/20\mu s, Fwd$		8.0	11.0	V
		$I_{PP}=2A, t_p=8/20\mu s, Fwd$		9.7	13.0	V
Dynamic Resistance	$R_{DYN}$	$(V_{C2} - V_{C1}) / (I_{PP2} - I_{PP1})$		1.7		$\Omega$
ESD Withstand Voltage <sup>1,2</sup>	$V_{ESD}$	IEC61000-4-2 (Contact)	$\pm 1b$			kV
		IEC61000-4-2 (Air)	$\pm 30$			kV
Diode Capacitance <sup>1</sup>	$C_D$	Reverse Bias=0V		12		pF
		Reverse Bias=2.5V		8		pF
		Reverse Bias=5V		7		pF

- $V_{ESD}$  is a measure of the robustness of the device. It is the maximum test voltage that can be sustained without damaging the device. The test conditions are specified.



# Key Parameters: $I_P$ or $I_{PP}$

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## Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$I_P$	Peak Current ( $t_p=8/20\mu s$ )	4.5	A
$T_{OP}$	Operating Temperature	-40 to 85	$^{\circ}C$
$T_{STOR}$	Storage Temperature	-50 to 150	$^{\circ}C$

- The Peak Current or  $I_P$  (or sometimes  $I_{pp}$ ) is the maximum peak current that can be applied to the ESD protector without damaging the device. The surge waveform conditions are always specified. Sometimes, several surge waveforms are specified:

## Absolute Maximum Ratings

Parameter	Rating	Units
Peak Pulse Current (8/20 $\mu s$ )	150	A
Peak Pulse Power (8/20 $\mu s$ )	2800	W
IEC 61000-4-2, Direct Discharge, (Level 4)	8	kV
IEC 61000-4-2, Air Discharge, (Level 4)	15	kV
IEC 61000-4-5 (8/20 $\mu s$ )	100	A
Bellcore GR 1089 (Intra-Building) (2/10 $\mu s$ )	100	A
ITU K.20 (5/310 $\mu s$ )	40	A



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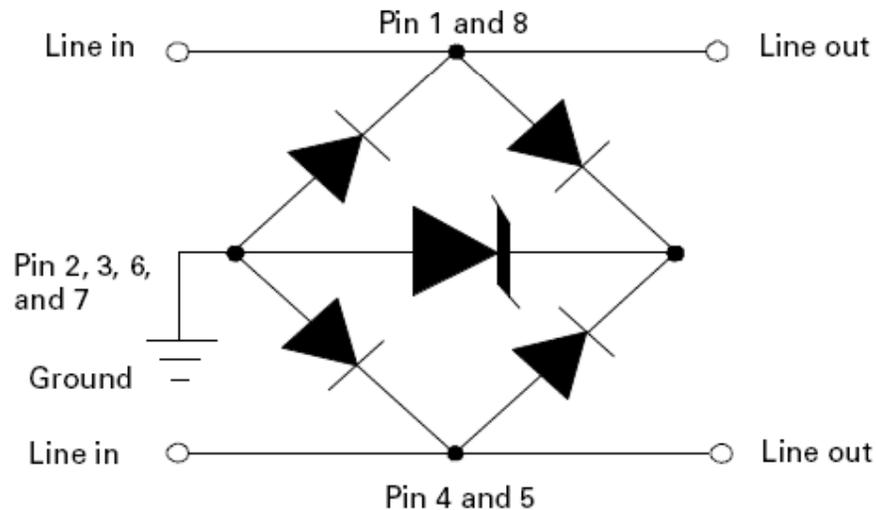


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# Grounded TVS Diode Arrays (SP03)

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Capacitance Range: 8pF-16pF (typical)

ESD Range: 30kV (contact discharge)

Lightning Range: 100-150A

Applications: Broadband Protection (i.e. 10/100/1000 Base T Ethernet)

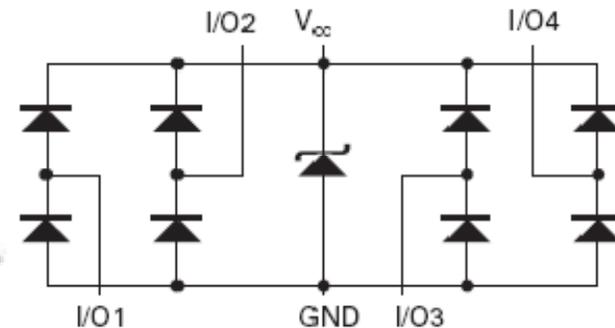
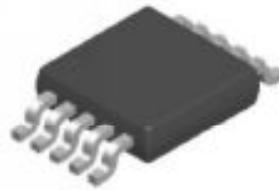
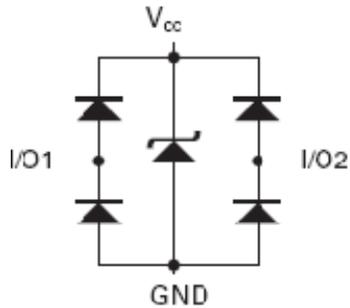


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# TVS Rail Clamp Diode Arrays (SP30xx, SP40xx)

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Capacitance Range: 0.40pF-2.4pF (typical)

ESD Level:  $\pm 8$ -30kV (contact discharge)

Lightning Range: 2.5-10A

Applications: HDMI, USB2.0/3.0, and Ethernet PHY protection

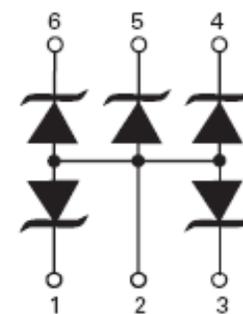
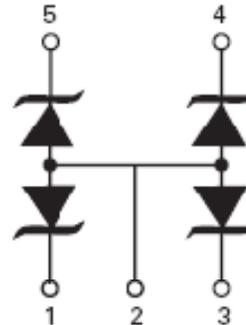
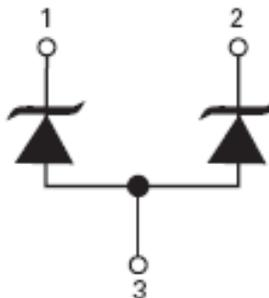


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# TVS Arrays (SP10xx, SP050x)

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Capacitance Range: 3.5pF-30pF (typical)

ESD Level:  $\pm 8$ -30kV (contact discharge)

Lightning Range: 2-10A

Applications: Keypads, audio lines, and general low-speed bus protection

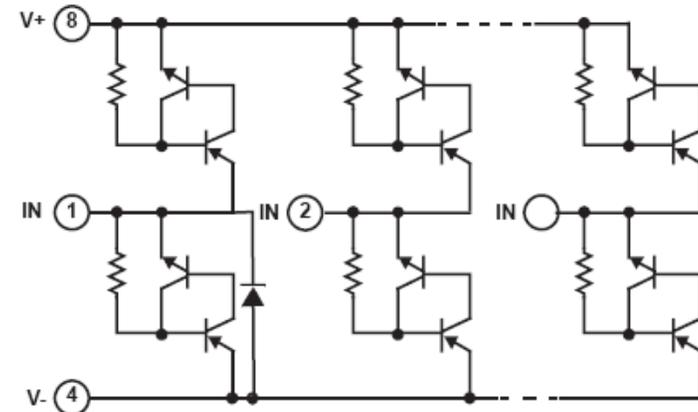
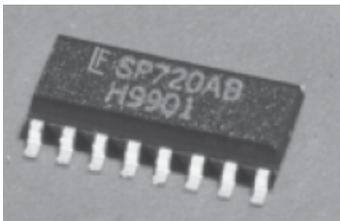
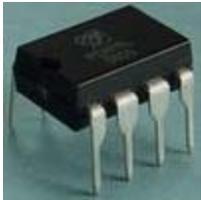


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# SCR Array Rail Clamps (SP72x)

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Capacitance Range: 3pF-5pF (typical)

ESD Level:  $\pm 4$ -8kV (contact discharge)

Lightning Range: 3-14A

Applications:  $\mu$ P Logic Inputs and general low-speed bus protection

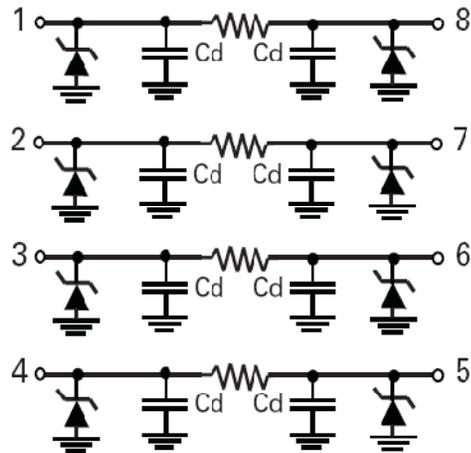


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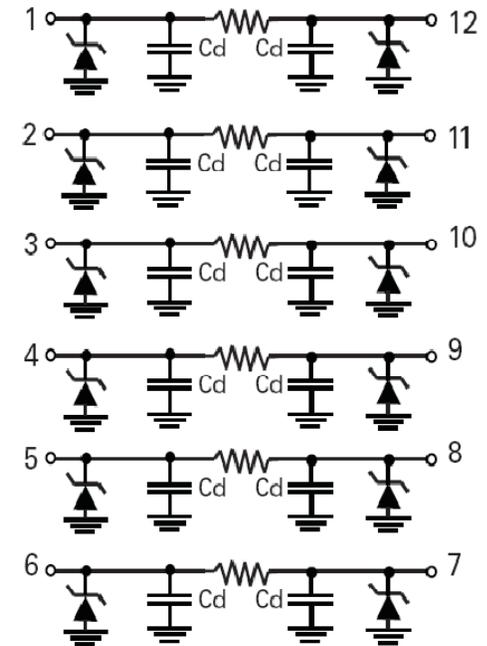
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# EMI Filter Arrays (SP60xx)



EMI Filter Arrays not only provide ESD protection, but also serve as low-pass filters to get rid of unwanted high-frequency signals (i.e. cellular band from 800MHz-2GHz).



Capacitance Range: 7pF-15pF (typical single Cd)

ESD Level:  $\pm 15$ -30kV (contact discharge)

Applications: Keypad and display interfaces for portable/mobile devices



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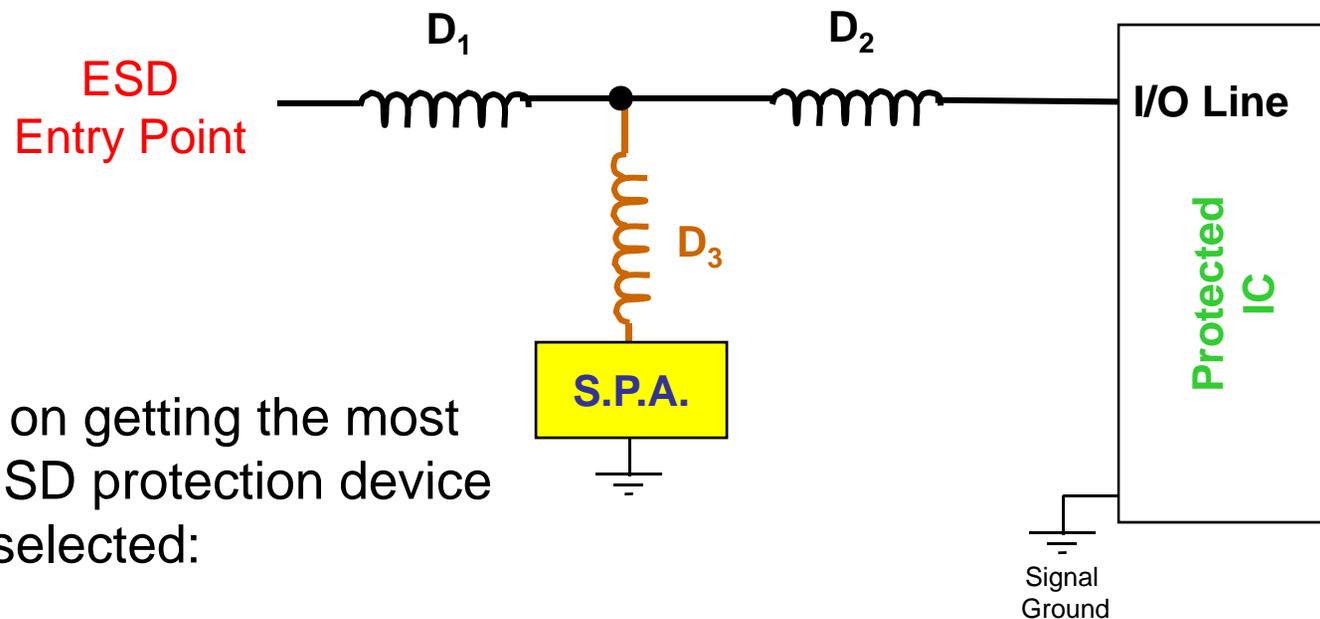


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# PC Board Layout Considerations

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Some tips on getting the most from the ESD protection device you have selected:

- **Minimize D1** – Place protection near entry connector
- **Maximize D2** – For best coordination with on-chip ESD protection
- **Minimize D3** – Stub traces should be avoided



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# Combining Protection Channels

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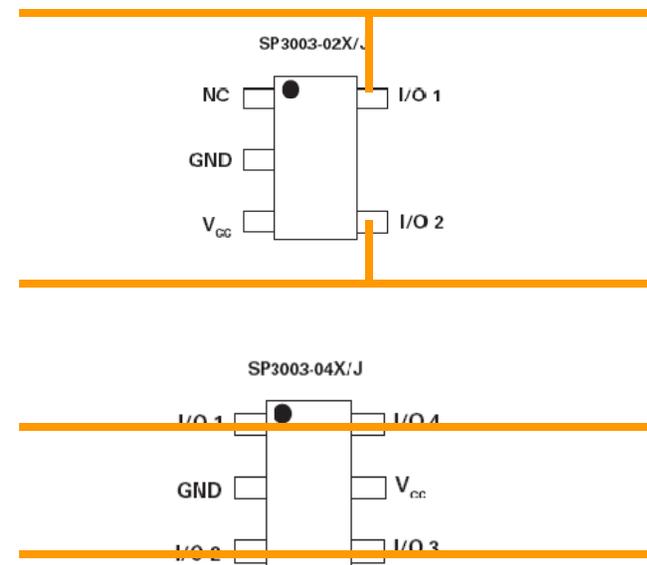


It is possible to combine protection channels to achieve higher surge capability:

For example, a customer loves the SOT553 package of the SP3003-02XTG, but needs a bit more  $V_{ESD}$  capability. You could use an SP3003-04XTG and combine the four channels into two. (As a bonus, the package becomes stub-less through-line!)

Of course the capacitance will double, but this may be acceptable.

A further benefit is the clamping voltage for a particular test waveform will be lower when channels are combined.



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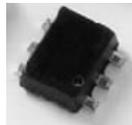
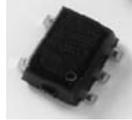
# Micro Packages



SC70



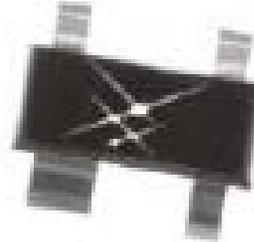
SOT5x3



SOT23



SOT143



SOD723



uDFN

Available in Series: SP10xx, SP30xx, SP050x, SP60xx



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# MSOP Packages

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## MSOP-8



## MSOP-10



**Available in Series: SP050x, SP30xx, SP40xx**

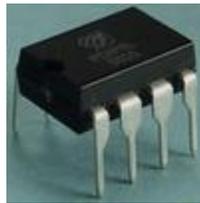


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# Power Packages

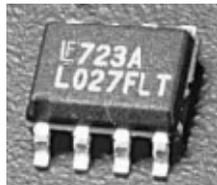
CIRCUIT  
PROTECTION  
SOLUTIONS



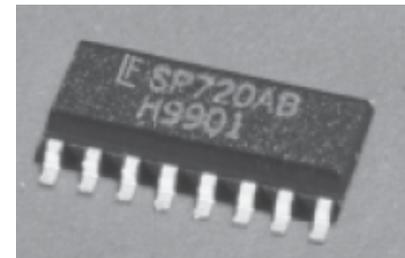
PDIP-8



PDIP-16



SOIC-8



SOIC-16

Available in Series: **SP72x, SP03-x**



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**Thank You!**



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